MULTI-PORT PRODUCTS
Ordering Information
Package Description Table

<table>
<thead>
<tr>
<th>IDT ID</th>
<th>Abbr</th>
<th>Description</th>
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<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>C</td>
<td>Sd</td>
<td>Ceramic Dual In-line Package</td>
<td>DG</td>
<td>PBGA</td>
<td>Plastic Ball Grid Array</td>
</tr>
<tr>
<td>F</td>
<td>Flat</td>
<td>Ceramic Flat Package</td>
<td>F</td>
<td>PDAF</td>
<td>Plastic Dual In-line Package</td>
</tr>
<tr>
<td>CL</td>
<td>CLCC</td>
<td>Ceramic Leadless Chip Carrier</td>
<td>J</td>
<td>PLCC</td>
<td>Plastic Loaded Chip Carrier</td>
</tr>
<tr>
<td>L</td>
<td>LCC</td>
<td>Ceramic Leadless Chip Carrier</td>
<td>DR</td>
<td>PQQP</td>
<td>Plastic Quad Flat Package</td>
</tr>
<tr>
<td>G</td>
<td>CGA</td>
<td>Ceramic Pin Grid Array</td>
<td>PQF</td>
<td>PQFP</td>
<td>Plastic Quad Flat Package</td>
</tr>
<tr>
<td>BC</td>
<td>CABGA</td>
<td>Chip Array Ball Grid Array</td>
<td>DD</td>
<td>TCQP</td>
<td>Thin Quad Flat Package</td>
</tr>
<tr>
<td>EY</td>
<td>VCQGA</td>
<td>Chip Array Very Thin Ball Grid Array</td>
<td>FF</td>
<td>TCQP</td>
<td>Thin Quad Flat Package</td>
</tr>
<tr>
<td>EF</td>
<td>FFBGA</td>
<td>Fine Fitch Ball Grid Array</td>
<td>FRF</td>
<td>TCQP</td>
<td>Thin Quad Flat Package</td>
</tr>
<tr>
<td>G</td>
<td>PGA</td>
<td>Fin Grid Array</td>
<td>TF</td>
<td>TCQP</td>
<td>Thin Quad Flat Package</td>
</tr>
</tbody>
</table>

Shipping Type: Optional 8 suffix at end of part number indicates Tape & Reel packaging

8 = Tape & Reel
Blank = Tube or Trays

Temperature
None: Commercial 0° C to +70° C
I: Industrial -40° C to +85° C
B: Military: -55° C to +125° C, compliant to MIL PRF 38535

Green
None = Standard Packaging
G = Green packaging

Package
See package description table above.

Speed
Guaranteed minimum performance measured in nanoseconds or MHz

Power
S = Standard power
L= Low power

Device Type
Refer to current datasheet

Voltage
None = 5.0 V
V = 3.3 V
T = 2.5 V
P = 1.8 V

Product Family
70
71

A = Alpha character
N = Numeric character